LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVE
A	Add device type O2. Add packages J and 3 for device type O2. Editorial changes throughout.	93-02-16	Monica L. Poel

# THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

				<del>,                                     </del>								<del>,</del>					,	,		
REV															<u> </u>					
SHEET																				
REV	A																			
SHEET	15			_																
	REV STATUS			RE	٧		A	A	A	A	A	A	A	A	A	A	А	Α	А	A
OF SHEETS				SH	SHEET 1 2 3			4	5	6	7	8	9	10	11	12	13	14		
PMIC N/A					ARED B	-				DEFENSE ELECTRONICS SUPPLY CENTER					-					
MIL	David Queenan  CHECKED BY  DRAWING  Dan DiCenzo  APPROVED BY  APPROVED BY  Nelson Hauck					DAYTON, OHIO 45444														
FOR USE BY						MICROCIRCUIT, DIGITAL, ADVANCED, SCHOTTKY TTL, ARITHMETIC LOGIC UNIT, MONOLITHIC SILICON								т,						
	•		-			PROVAL	DATE													
AMSC N/A				00-10	86-10-06			sizi	Ε		E COI			59	5962-86710					
				REVI	SION L	EVEL				A			726	8						
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DESC FORM 193

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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E100-93

### 1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
  - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	54F381	4-bit arithmetic logic unit
02	54F181	4-bit arithmetic logic unit

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
J	GDIP1-T24 or CDIP2-T24	24	Dual-in-line package
R	GDIP1-T20 or CDIP2-T20	20	Dual-in-line package
S	GDFP2-F20 or CDFP3-F20	20	Flat package
2	CQCC1-N2O	20	Square leadless chip carrier
3	CQCC1-N28	28	Square leadless chip carrier

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

1/ Must withstand the added P<sub>D</sub> due to short circuit test, e.g., I<sub>OS</sub>.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-86710
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## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and bulletin</u>. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

**STANDARDS** 

**MILITARY** 

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

#### REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
  - 3.2.3 <u>Truth tables</u>. The truth tables shall be as specified on figure 2.
  - 3.2.4 Logic diagrams. The logic diagrams shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

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	Symbol	Con	ditions	Group A	Device	<u>L1</u>	mits	   Unit
		-55°C ≤ unless other	T <sub>C</sub> ≤ +125°C wise specified	subgroups	type	Min	Max	
High level output voltage	V <sub>ОН</sub>	V <sub>CC</sub> = 4.5 V I <sub>OH</sub> = -1.0 mA V <sub>IN</sub> = 0.8 V o	r 2.0 V	1,2,3	ALL	2.5		V
Low level output voltage	v <sub>oL</sub>	V <sub>CC</sub> = 4.5 V   I <sub>OL</sub> = 20 mA   V <sub>IN</sub> = 0.8 V or	~ 2.0 V	1,2,3	ALL		0.5	V
Input clamp voltage	v <sub>IC</sub>	  V <sub>CC</sub> = 4.5 V  I <sub>IN</sub> = -18 mA  T <sub>C</sub> = +25°C		1	ALL		-1.2	V
High level input current	I <sub>IH1</sub>	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 2.7 V		1,2,3	ALL		20	   μ <b>Α</b> 
	I IH2	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 7.0 V		1,2,3	ALL		100	μΑ
Low level input current	IIL	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 0.5 V	S <sub>O</sub> -S <sub>2</sub> inputs	1,2,3	01		-0.6	m.A
			Other inputs		ļ		-2.4	
			M input	1,2,3	02		-0.6	
			A <sub>n</sub> , B <sub>n</sub> inputs				-1.8	 
			S <sub>n</sub> inputs				-2.4	
			C <sub>n</sub> inputs				-3.0	
Short circuit output current	Ios	  V <sub>CC</sub> = 5.5 V  V <sub>OUT</sub> = 0.0 V	1/	1,2,3	ALL	-60	-150	mA
Supply current	Icc	V <sub>CC</sub> = 5.5 V		1,2,3	01		89	mA
		S <sub>0</sub> -S <sub>3</sub> = GND  Other inputs h	igh		02		65	
Functional tests		See 4.3.1c		7	ALL			
See note at end of table.	-							
_								
STANDA MILITARY DEFENSE ELECTRONI	RDIZED DRAWING	, CENTED	SIZE			<del></del>	5962	-8671

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Test	Symbol	Conditions	  Grou		  Device	Li	mits	   Unit
		-55°C ≤ T <sub>C</sub> ≤ +125°C unless otherwise specified	subg	roups	type	Min	Max	<u> </u>
Propagation delay time,	t <sub>PLH1</sub>	V <sub>CC</sub> = 5.0 V		9	01		12	ns
c <sub>n</sub> to F <sub>1</sub>		$ R_L  = 500\Omega$ $ C_L  = 50 pF minimum$  See figure 4.	10	,11			15	<u> </u>
	t <sub>PHL1</sub>	See figure 4.		9	01		8	ns
			_10	,11			12	
Propagat <u>i</u> on delay time, C <sub>n</sub> to F <sub>n</sub>	t <sub>PLH2</sub>			9	02	3.0	8.5	ns
n to in			10	,11		2.5	16.0	   
	t <sub>PHL2</sub>			9	02	3.0	8.5	ns
			10	,11		2.5	12.0	! [
Propagation delay time, any A or B to any F	t <sub>PLH</sub> 3			9	01		15	l   ns
any it as a so only i		 	10	,11			19 1	<u> </u>
	t <sub>PHL</sub> 3		<u> </u>	9	01		13	l   ns
			10	,11			16	
Propagation_delay time, any A or B to any F	t <sub>PLH4</sub>			9	02	4.0	10.5	l   ns
(mode = sum)			10	,11		3.5	16.5	<u> </u> 
	t <sub>PHL4</sub>			9	02	4.0	10.0	l ns
			10	,11		4.0	13.5	<u> </u> 
Propag <u>a</u> tion_delay ti <u>m</u> e, any A or B to any F	t <sub>PLH5</sub>			9	02	4.0	12.0	l   ns
(mode = dif)			10_	,11		3.5	17.5	   
	t <sub>PHL5</sub>			9	02	3.0	12.0	ns
			10	,11		3.0	14.0	1
Propagation delay time, S <sub>1</sub> to F <sub>1</sub>	t <sub>PLH6</sub>			9	01		20	ns
91 09 11		   	10	,11			24	 
	t <sub>PHL6</sub>			9	01		14	ns
			10	,11			17	<u> </u>
Propagation de <u>l</u> ay time, A <sub>1</sub> or B <sub>1</sub> to G	t <sub>PLH7</sub>	   		9	01		12	ns
<sub> </sub> 5, 5 <sub>1</sub> to 0		 	10	,11			14	<u> </u>
	t <sub>PHL7</sub>	 		9	01		   10	ns
See note at end of table.			10	,11	<u> </u>		14	
		1	<u> </u>				<del></del>	
MILITARY		G	ZE				5962	2-8671
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444						· · · · · · · · · · · · · · · · · · ·	+	

Test	Symbol	Condition		Group A	  Device	   <u>Li</u>	mits_	Unit
		-55°C ≤ T <sub>C</sub> ≤ unless otherwise	<pre>5 +125°C specified</pre>	subgroups	type	Min	Max	
Pr <u>o</u> paga <u>t</u> ion <u>d</u> elay time, A or B to G	t <sub>PLH8</sub>	   V <sub>CC</sub> = 5.0 V		9	   02	2.5	7.5	_ ns
(mode = sum)		$V_{CC} = 5.0 \text{ V}$ $R_L = 500\Omega$ $C_L = 50 \text{ pF minimu}$ $See \text{ figure 4.}$	ım	10,11	<u> </u>	2.5	9.0	ļ
	t <sub>PHL8</sub>	i see rigure 4.		9	   02	2.5	7.5	   ns
				10,11	 	2.5	9.5	1
Propagation delay time, A or B to G	t <sub>PLH9</sub>			9	02	3.0	9.0	ns
(mode = dif)				10,11	! 	2.5	11.5	<u> </u>
	t <sub>PHL9</sub>			9	02	2.5	9.5	ns
				10,11		2.5	11.0	
Propagation de <u>l</u> ay time, A <sub>1</sub> or B <sub>1</sub> to P	t <sub>PLH10</sub>			9	01	 	11	ns
1 1 22 2				10,11	 	! 	15	1
	t <sub>PHL10</sub>			9	01		10	ns
				10,11			13	<u> </u>
Propagation delay time, A or B to P (mode = sum)	t <sub>PLH11</sub>			9	02	2.5	7.0	l ns
				10,11	-	2.5	8.5	
	t <sub>PHL11</sub>			9	02	3.0	7.5	ns
				10,11		3.0	9.5	
Pr <u>o</u> paga <u>t</u> ion <u>d</u> elay time, A or B to P	t <sub>PLH12</sub>			9	02	2.5	8.0	ns
(mode = dif)	ļ			10,11		2.5	11.0	
	t <sub>PHL12</sub>			9	02	3.0	8.5	ns
				10,11		3.0	111.0	<u> </u>
Propagat <u>i</u> on d <u>e</u> lay time, S <sub>1</sub> to G or P	t <sub>PLH13</sub>			9	01		14	ns
o <sub>1</sub> to a o				10,11			19	
	t <sub>PHL13</sub>			9	01		14	ns
				10,11			19	<u> </u>
Pr <u>o</u> paga <u>t</u> ion delay time, A or B to A=B	t <sub>PLH14</sub>			9	02	_11	27	ns
(mode = dif)	ļ			10,11		8	] ] <b>3</b> 5	<u> </u>
	t <sub>PHL14</sub>			9	02	5.5	13.5	ns
See note at end of table.				10,11		5.5	21.0	l I
				<u> </u>			1	
STANDA MILITARY DEFENSE ELECTRON:	RDIZED DRAWING	V CENTED	SIZE A				5962	2-8671
DEFENSE ELECTRON. DAYTON, O	LI CENTEK			· · · · · · · · · · · · · · · · · · ·		<del>                                     </del>		

Test	Symbol		Group A	Device	Li	imits	 _  Unit
		-55°C ≤ T <sub>C</sub> ≤ +125°C unless otherwise specified	subgroups	•	Min	Max	
Propagation delay time, A. or B. to F.	t <sub>PLH15</sub>	V <sub>CC</sub> = 5.0 V	9	 _  02	3.0	9.0	ns
A <sub>i</sub> or B <sub>i</sub> to F <sub>i</sub> (mode = sum)		$V_{CC} = 5.0 \text{ V}$ $R_L = 500\Omega$ $C_L = 50 \text{ pF minimum}$ $See figure 4.$	10,11		3.0	14.5	<u> </u>
	t <sub>PHL15</sub>	See Tigure 4.	9	_  02	3.0	10.0	 _  ns
			10,11	'	3.0	14.5	ļ
Propagation delay time, A; or B; to F;	t <sub>PLH16</sub>		99	_  02	3.0	11.0	_  ns
A <sub>i</sub> or B <sub>i</sub> to F <sub>i</sub> (mode = dif)			10,11		3.0	17.5	<u> </u>
	<sup>t</sup> PHL16		9	_ 02	3.0	11.0	│ _│ ns
			10,11	ļ'	3.0	14.5	-
Propagation delay time, A or B to C <sub>n+4</sub> (mode = sum)	t <sub>PLH17</sub>		9	_ 02	5.0	13.0	ns
(mode = sum)	j		10,11		5.0	15.5	-
	t <sub>PHL</sub> 17		9	_ 02	3.5	12.0	ns
			10,11	<u> </u>	3.5	16.5	1.
Propagation delay time, A or B to C (mode = dif)	t <sub>PLH18</sub>		9	02	5.0	14.0	ns
(mode = dif)	<u> </u> '		10,11	ļi	5.0	17.0	1
	t <sub>PHL18</sub>		9	02	5.0	13.0	ns
			10,11	<u> </u>	4.0	15.0	<del> </del>
Propagation delay time,  C <sub>n</sub> to C <sub>n+4</sub>	t <sub>PLH19</sub>	İ	9	02	3.0	8.5	l ns
. " "			10,11	<u> </u>	3.0	10.0	<u> </u>
	t <sub>PHL19</sub>	<u> </u> 	9	02	3.0	8.0	ns
			10,11	<u> </u>	3.0	9.5	1
Propagation delay time, A or B to F	t <sub>PLH20</sub>		9	02	3.5	9.5	ns
(mode = logic)			10,11	<del>                                     </del>	3.5	14.5	<u> </u>
	t <sub>PHL20</sub>		9	02	3.0	10.0	ns
		<u></u>	10,11	į į	3.0	15.5	i

 $<sup>\</sup>underline{1}$ / Not more than one output should be shorted at one time, and the duration of the short circuit condition should not exceed 1 second.

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Device type	02	01	02
Case outline	J	R, S, and 2	3
Terminal number	Teri	minal symbol	
1 2 3 4 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28	B  4	A110001201D SSTER FIGIP CBABAVCC	21 B 4 8 8 8 8 8 8 2 2 1 F 1 F 1 8 2 8 1 B 4 1 B 1 8 1 B 1 A 1 B 1 B 1 B 1 B 1 B 1 B 1 B 1 B

NC = No connection

FIGURE 1. <u>Terminal connections</u>.

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Device type 01

			Inp	uts						Output	s	
Function	s <sub>o</sub>	s <sub>1</sub>	s <sub>2</sub>	c <sub>n</sub>	An	B <sub>n</sub>	Fo	F <sub>1</sub>	F <sub>2</sub>	F <sub>3</sub>	G	P
Clear	0	0	0	х	х	Х	0	0	0	0	0	0
B minus A	1	0	0	0 0 0 1 1 1	0 0 1 1 0 0 1	0 1 0 1 0 1	1 0 0 1 0 1	1 0 1 0 1 0	1 0 1 0 1 0	1 0 1 0 1 0	1 0 1 1 1 0	0 0 1 0 0 0
A minus B	0	1	0	0 0 0 1 1 1	0 0 1 1 0 0 1	0 1 0 1 0 1	1 0 0 1 0 1	1 0 1 1 0 0	1 0 1 1 0 0 1	1 0 1 1 0 0	1 0 1 1 1 0	0 1 0 0 0 1 0
A plus B	1	1	0	0 0 0 0 1 1 1	0 0 1 1 0 0 1	0 1 0 1 0 1 0	0 1 1 0 1 0	0 1 1 0 0	0 1 1 1 0 0	0 1 1 1 0 0	1 1 0 1 1 1	1 0 0 0 1 0 0
а⊕в	0	0	1	X X X	0 0 1 1	0 1 0 1	0 1 1 0	0 1 1 0	0 1 1 0	0 1 1 0	1 1 1 0	1 1 0 0
A + B	1	0	1	X X X	0 0 1 1	0 1 0 1	0 1 1	0 1 1 1	0 1 1 1	0 1 1	1 1 1	1 1 1 0
AB	0	1	1	X X X	0 0 1 1	0 1 0 1	0 0 0 1	0 0 0 1	0 0 0 1	0 0 0 1	0 1 0 1	0 1 0 0
Preset	1	1	1	X X X	0 0 1 1	0 1 0 1	1 1 1	1 1 1	1 1 1	1 1 1	1 1 1	1 1 1 0

<sup>1 =</sup> High voltage level
0 = Low voltage level
X = Immaterial

FIGURE 2. <u>Truth tables</u>.

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## Device type 02

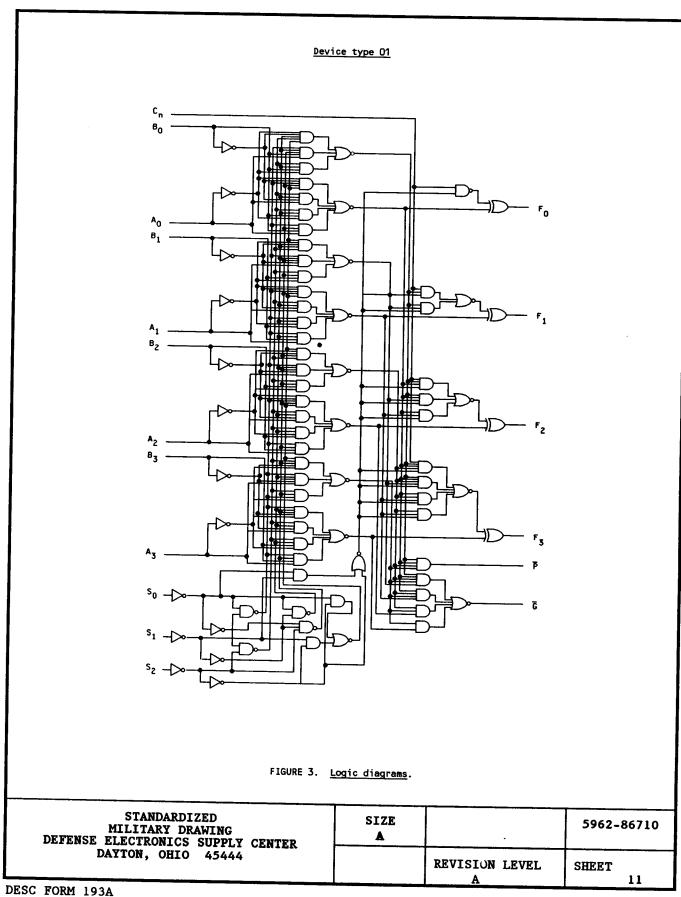
	Solos	tion		Active low data and F <sub>n</sub> outputs				
	Selection			Logic function	Arithmetic operations (M = H)			
<b>S</b> 3	\$2	<b>S</b> 1	s0	(M = H)	C <sub>n</sub> = inactive (no carry)	C <sub>n</sub> = active (carry)		
	L L L H H H H L L L L H H			F = AB F = A + B F = 1 + B F = A + B F = AB + B F = AB + B F = AB + B F = AB + B F = B + B	F = A MINUS 1 F = AB MINUS 1 F = AB MINUS 1 F = MINUS 1 (2's COMP) F = A PLUS (A + B) F = A MINUS B MINUS 1 F = A HINUS B MINUS 1 F = A PLUS (A + B) F = A PLUS B F = AB PLUS (A + B) F = AB PLUS A F = AB PLUS A F = AB PLUS A	F = A F = AB F = AB F = AB F = ZERO F = A PLUS (A + B) PLUS 1 F = AB PLUS (A + B) PLUS 1 F = A MINUS B F = (A + B) PLUS 1 F = A PLUS (A + B) PLUS 1 F = A PLUS B PLUS 1 F = AB PLUS (A + B) PLUS 1 F = (A + B) PLUS 1 F = AB PLUS A PLUS 1 F = AB PLUS A PLUS 1 F = AB PLUS A PLUS 1		
H	н н	H	 Н	F = AB F = A	F = AB PLUS A F = A	F = AB PLUS A PLUS 1 F = A PLUS 1		

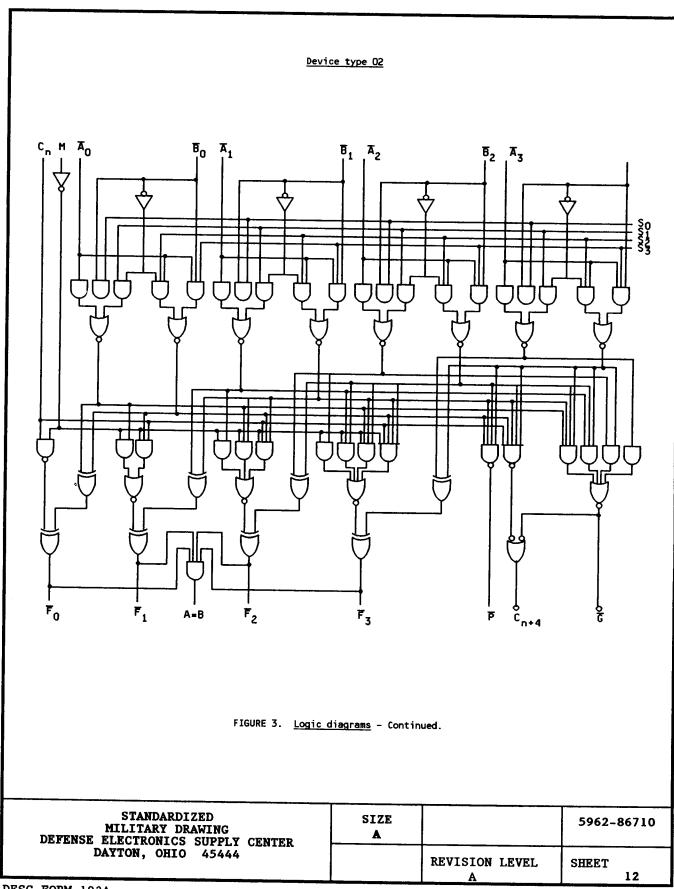
	Selec	tion		Active high data and F <sub>n</sub> outputs				
	Setec	t ion		Logic function	Arithmetic operations (M = H)			
s3	s2	s1	s0	(M = H)	C <sub>n</sub> = inactive (no carry)	C <sub>n</sub> = active (carry)		
	L L L L H H H H L L L L H H H	L		F = A + B F = AB	F = A F = A + B F = A + B F = MINUS 1 (2's COMP) F = A PLUS AB F = A MINUS B MINUS 1 F = A MINUS B MINUS 1 F = A PLUS AB F = A PLUS B F = A PLUS B F = AB MINUS 1 F = AB MINUS 1 F = A PLUS AB F = A PLUS AB F = (A + B) PLUS AB F = (A + B) PLUS A F = (A + B) PLUS A	F = A PLUS 1 F = (A + B) PLUS 1 F = (A + B) PLUS 1 F = ZERO F = A PLUS AB PLUS 1 F = A MINUS B F = AB F = A PLUS AB PLUS 1 F = A PLUS B PLUS 1 F = (A + B) PLUS AB PLUS 1 F = AB F = A PLUS A PLUS 1 F = (A + B) PLUS A PLUS 1 F = (A + B) PLUS A PLUS 1 F = (A + B) PLUS A PLUS 1		

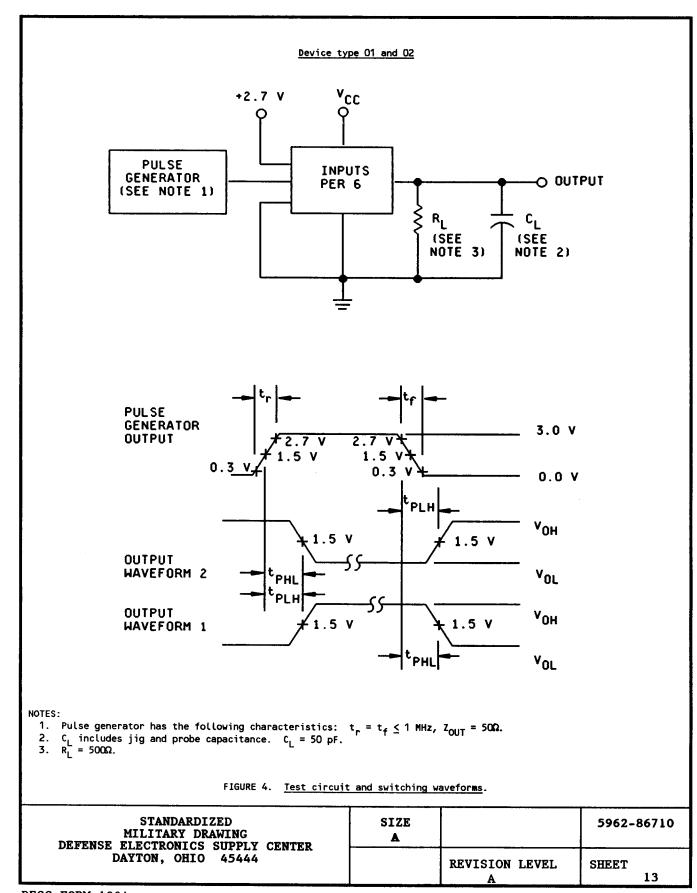
H = High voltage level
L = Low voltage level

FIGURE 2. <u>Truth tables</u> - Continued.

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- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-N-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall include the requirements for inputs, outputs, biases, and power dissipation, as applicable, in accordance with the specified purpose of method 1015 of MIL-STD-883.
    - (2)  $T_A = +125$ °C, minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 9, 10, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1.

<sup>\*\*</sup> Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

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- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 7 shall include verification of the truth table.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
      - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall include the requirements for inputs, outputs, biases, and power dissapation, as applicable, in accordance with the specified purpose of method 1015 of MIL-STD-883.
      - (2)  $T_{\Delta} = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
  - 5. PACKAGING
  - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
  - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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